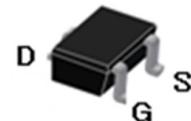
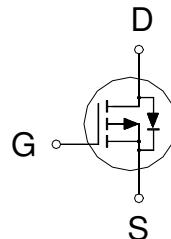


P-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

$BV_{DSS}$	-30V
$R_{DS(on)}(\text{MAX.})$	125m $\Omega$
$I_D$	-3.1A



Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$  Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_A = 25^\circ\text{C}$	$I_D$	-3.1	A
	$T_A = 70^\circ\text{C}$		-2.1	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	-12	
Power Dissipation	$T_A = 25^\circ\text{C}$	$P_D$	1.04	W
	$T_A = 70^\circ\text{C}$		0.66	
Operating Junction & Storage Temperature Range		$T_j, T_{stg}$	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Ambient <sup>3</sup>	$R_{\theta JA} (T \leq 10\text{sec})$		83	°C / W
	$R_{\theta JA} (\text{Steady State})$		120	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Duty cycle  $\leq 1\%$

<sup>3</sup>The device mounted on a 1 in<sup>2</sup> pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-30			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.0	-1.6	-3.0	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -24V, V_{GS} = 0V$			-1	$\mu\text{A}$
		$V_{DS} = -20V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			-10	
On-State Drain Current <sup>1</sup>	$I_{D(\text{ON})}$	$V_{DS} = -5V, V_{GS} = -10V$	-3.1			A
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(\text{ON})}$	$V_{GS} = -10V, I_D = -3.1\text{A}$		100	125	$\text{m}\Omega$
		$V_{GS} = -4.5V, I_D = -2\text{A}$		140	190	
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = -5V, I_D = -3\text{A}$		4.5		S
DYNAMIC						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = -15V, f = 1\text{MHz}$		294		pF
Output Capacitance	$C_{oss}$			41		
Reverse Transfer Capacitance	$C_{rss}$			24		
Total Gate Charge <sup>1,2</sup>	$Q_g$	$V_{DS} = -15V, V_{GS} = -10V, I_D = -2.7\text{A}$		6.3		nC
Gate-Source Charge <sup>1,2</sup>	$Q_{gs}$			0.8		
Gate-Drain Charge <sup>1,2</sup>	$Q_{gd}$			1.4		
Turn-On Delay Time <sup>1,2</sup>	$t_{d(on)}$	$V_{DS} = -15V, I_D = -1\text{A}, V_{GS} = -10V, R_{GS} = 6\Omega$		10		nS
Rise Time <sup>1,2</sup>	$t_r$			20		
Turn-Off Delay Time <sup>1,2</sup>	$t_{d(off)}$			15		
Fall Time <sup>1,2</sup>	$t_f$			12		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ( $T_c = 25^\circ\text{C}$ )						
Continuous Current	$I_s$				-2	A
Pulsed Current <sup>3</sup>	$I_{SM}$				-8	
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = I_s, V_{GS} = 0V$			1.2	V

<sup>1</sup>Pulse test : Pulse Width  $\leq 300\ \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

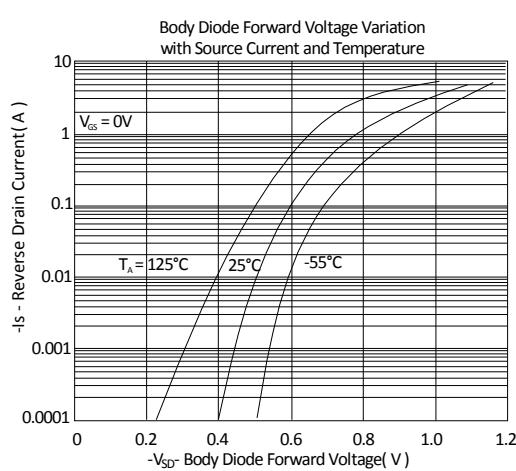
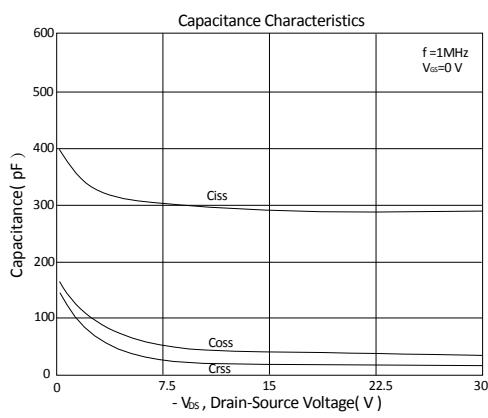
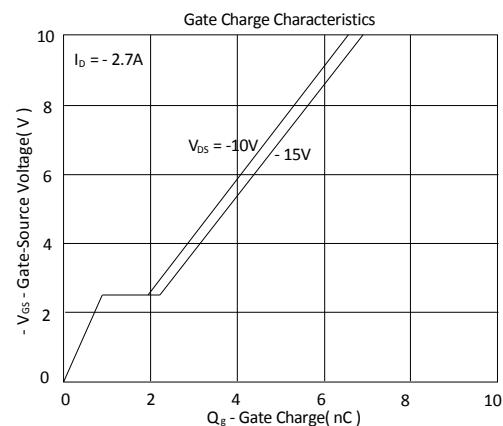
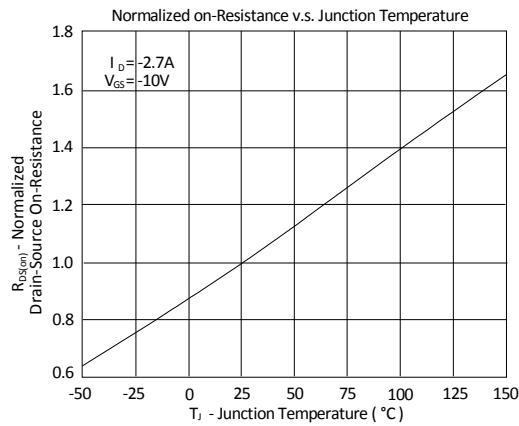
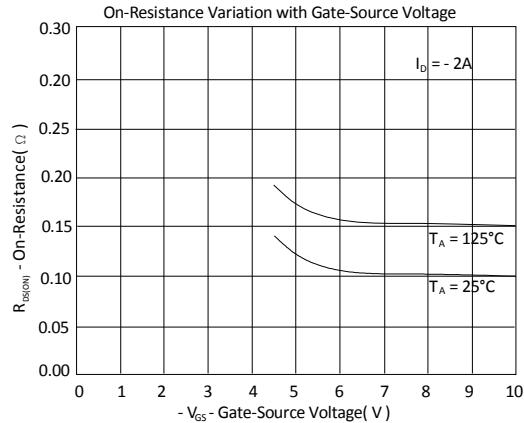
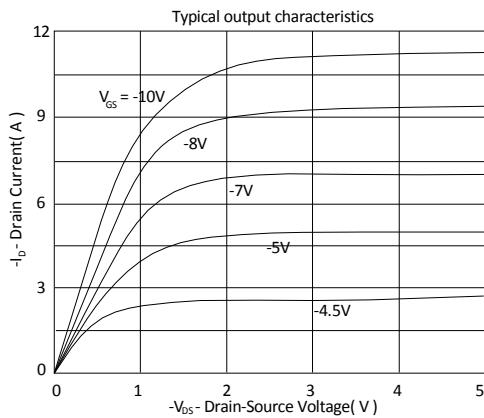
<sup>2</sup>Independent of operating temperature.

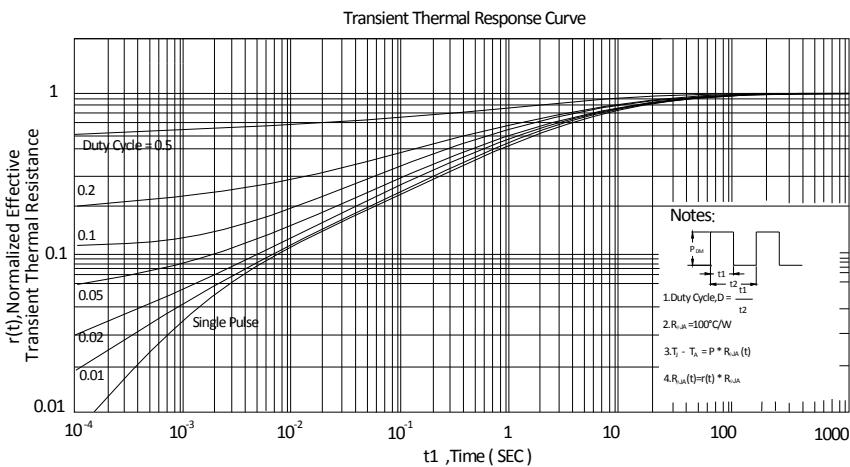
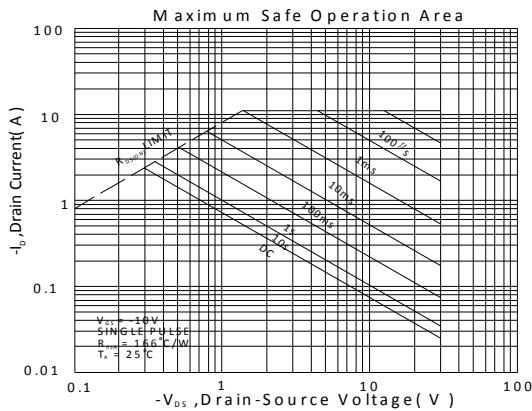
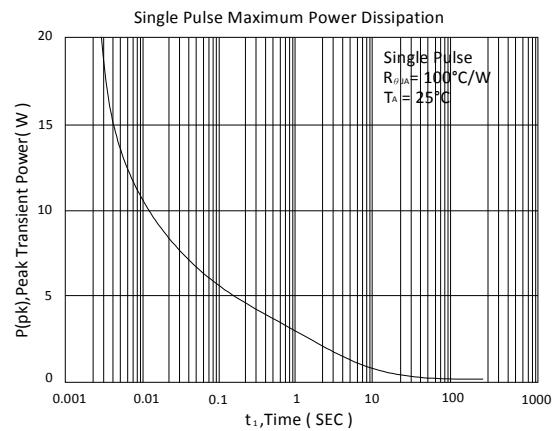
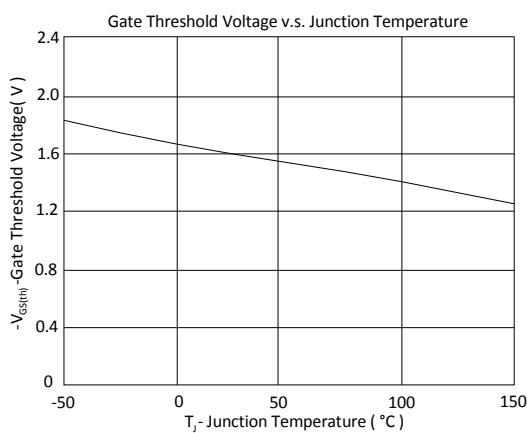
<sup>3</sup>Pulse width limited by maximum junction temperature.

EMC will review datasheet by quarter, and update new version.



TYPICAL CHARACTERISTICS

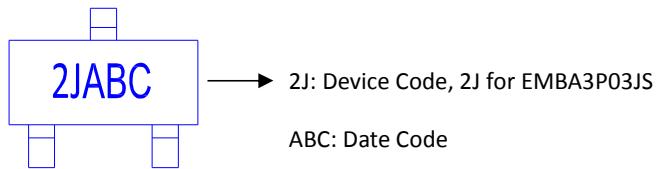




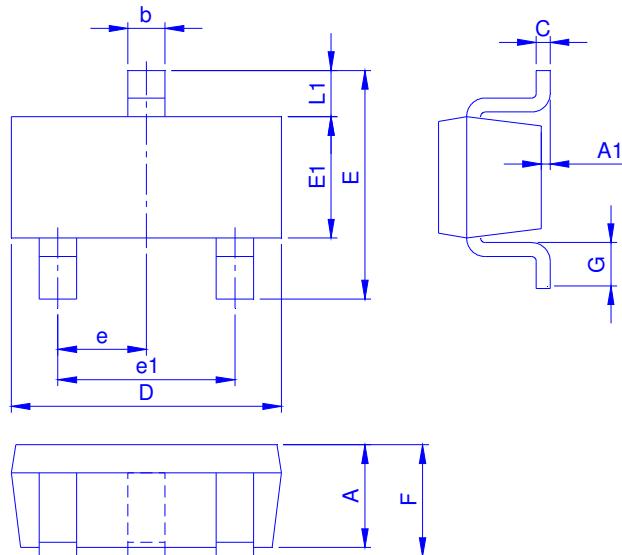


Ordering & Marking Information:

Device Name: EMBA3P03JS for SOT23-3



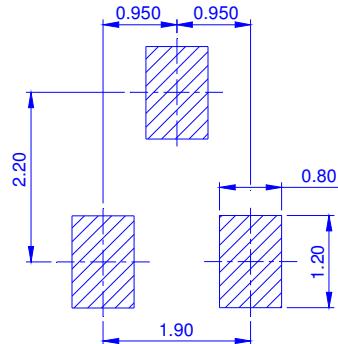
Outline Drawing



Dimension in mm

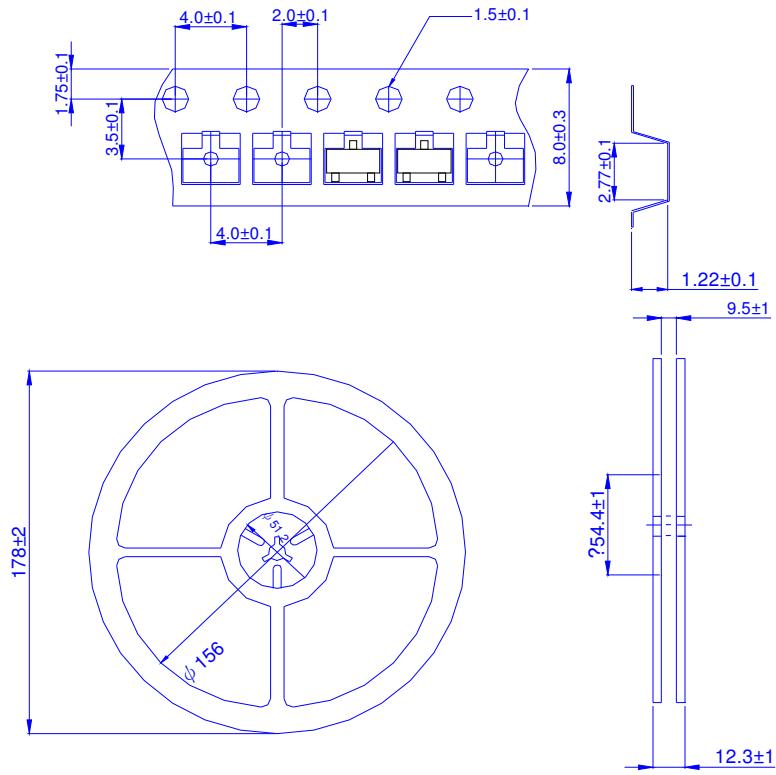
Dimension	A	A1	b	C	D	E	E1	e	e1	F	G	L1
Min.	0.70	-	0.30	0.080	2.80	2.10	1.20	0.90	1.80	0.80	0.30	0.54
Typ.	0.95	-	0.40	0.127	2.90	2.50	1.30	0.95	1.90	0.95	0.40	0.57
Max.	1.20	0.15	0.50	0.202	3.10	3.00	1.80	1.00	2.00	1.25	0.60	0.70

Footprint





- ◆ Tape&Reel Information:3000pcs/Reel(Dimension in millimeter)



產品別	SOT23-3
Reel 尺寸	7"
編帶方式	FEED DIRECTION 
前空格	50
後空格	50
裝箱數	
滿捲數量	3K
捲/內盒比	5 : 1
內盒滿箱數	15K
內/外箱比	12 : 1